

# CSX-750F series

(2,000pcs/reel)



## ■ FEATURES:

- Ultra-miniature low profile SMT package.
- Ceramic leadless chip carrier with seam-welded metal lid.
- Low power CMOS IC.
- Supply voltage 5.0V and 3.3V.
- Output enable function.
- Reflow soldering.
- Tape and reel packaging.

## ■ APPLICATIONS:

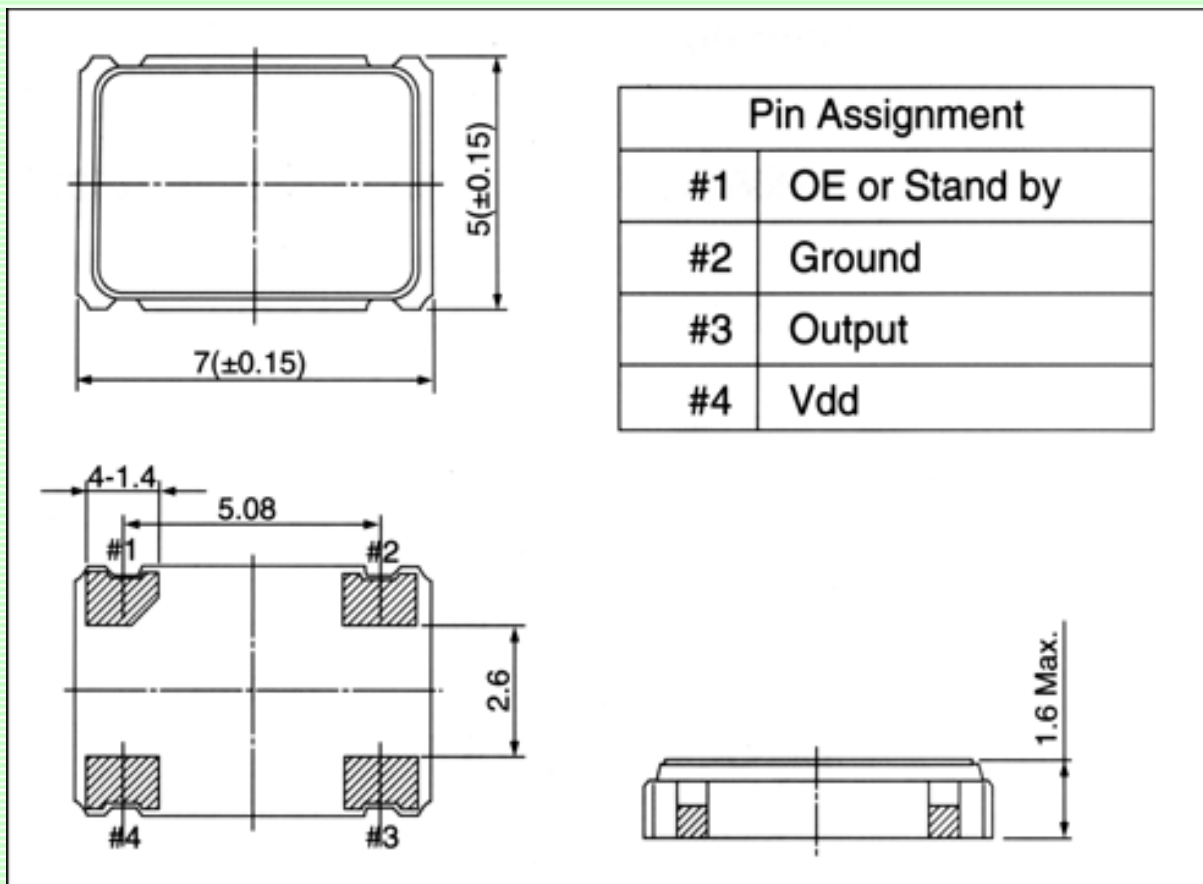
- Can be used for a wide range of applications including use in communication equipment, AV equipment, OA equipment and measuring instruments.

## □ STANDARD SPECIFICATIONS

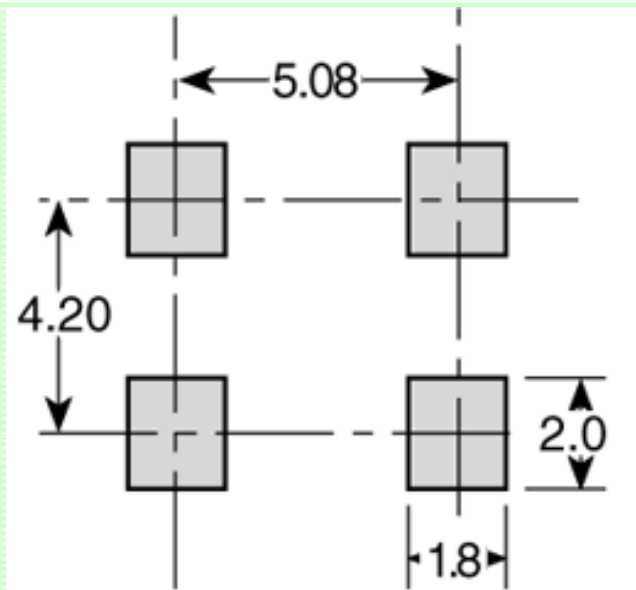
Item		CSX-750FC(*)		CSX-750FB(*)	CSX-750FJ(*)
Frequency range		1.000MHz to 39.999MHz	40.000MHz to 70.000MHz	1.000MHz to 39.999MHz	40.000MHz to 70.000MHz
Frequency stability		C:±100ppm B:±50ppm (-20°C to +70°C) F:±100ppm (-40°C to +85°C)			
Operating temperature range		-20°C to +70°C (-40°C to +85°C)			
Storage temperature range		-55°C to 125°C			
Supply voltage		Vdd: 5.0V±0.5V		Vdd: 3.3V±0.3V	
Supply current		25mA Max.	45mA Max.	15mA Max.	25mA Max.
Duty	TTL level(1.4V) CMOS level(V <sub>DD</sub> /2)	40% to 60% 45% to 55%		- 45% to 55%	
Output voltage	V <sub>OH</sub> V <sub>OL</sub>	4.0V Min 0.4V Max		2.2V Min 0.4V Max	
Output load	TTL CMOS	10TTL Max. 50pF Max.		- 30pF Max.	
Rise & Fall time	TTL CMOS	tr, tf: 8nsec Max.	tr, tf: 6nsec Max.	tr, tf: 8nsec Max.	- tr, tf: 6nsec Max.
Start up time		4msec Max.	10msec Max.	4msec Max.	10msec Max.
Input (OE) voltage		V <sub>IH</sub> : 2.0V Min. V <sub>IL</sub> : 0.8V Max.		V <sub>IH</sub> : 2.0V Min. V <sub>IL</sub> : 0.4V Max.	V <sub>IH</sub> : 0.7V <sub>DD</sub> Min. V <sub>IL</sub> : 0.3V <sub>DD</sub> Max.
Disable current	FC FB	10mA Max.	20mA Max.	5mA Max.	-
Stand-by current	FJ	-	-	-	10µA Max.
Shock resistance		±20ppm MAX. (75cm height drop on hardwood board 3 times.)			

NOTE: Please contact us for availability of TTL tight-duty and operating temperature range (-40°C - +85°C)

## ■ DIMENSIONS: (UNIT=mm)



**RECOMENDED SOLDERING PATTERN: (UNIT=mm)**



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